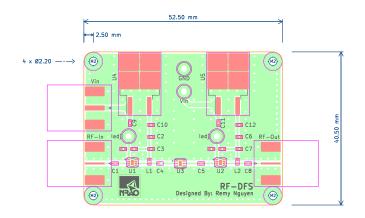
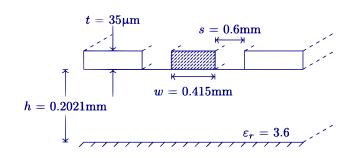
TOP-L1



Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0



BOARD CHARACTERISTICS

Copper Layer Count: 4 Board Thickness: 1.5670 mm

Board overall dimensions: 52.5000 mm x 40.5000 mm

Min track/spacing: 0.0000 mm / 0.0000 mm Min hole diameter: 0.3000 mm

Copper Finish: ENIG Impedance Control: Yes
Castellated pads: No Plated Board Edge: No

Edge card connectors: No

LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

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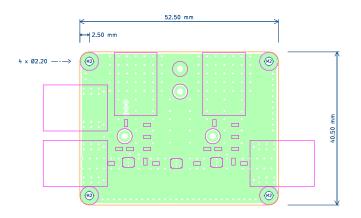
File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

 Size: A4
 Date: 1/23/2024
 Rev: B

 KiCad E.D.A. kicad 7.0.5
 Id: 1/1

IN-L2



Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1.5670 mm

Board overall dimensions: 52.5000 mm x 40.5000 mm

Min track/spacing: 0.0000 mm / 0.0000 mm Min hole diameter: 0.3000 mm

Copper Finish: ENIG Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Notes: LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

Size: A4 Date: 1/23/2024 Rev: B KiCad E.D.A. kicad 7.0.5 ld: 1/1

IN-L3 ← 2.50 mm **BOARD CHARACTERISTICS** Copper Layer Count: Board Thickness: 1.5670 mm Layer Name Type Material Thickness (mm) Color Epsilon R Loss Tangent Board overall dimensions: $52.5000 \text{ mm} \times 40.5000 \text{ mm}$ F.Silkscreen Top Silk Screen Liquid Photo 0 mm White Min track/spacing: 0.0000 mm / 0.0000 mm Min hole diameter: 0.3000 mm F.Paste Top Solder Paste 0 mm Copper Finish: ENIG Impedance Control: Yes F.Mask Top Solder Mask 0.0254 mm 3.3 Liquid Ink Purple 0 Castellated pads: Plated Board Edge: No No F.Cu copper 0.0432 mm 0 Edge card connectors: No FR408HR 2113 0.2021 mm FR4 natural 3.6 0.01 Dielectric 1 prepreq In1.Cu copper 0.0175 mm LNA footprint is pin-compatible with PMA2-123LN+. Dielectric 2 core FR408-HR 0.9906 mm FR4 natural 3.64 0.0098 In2.Cu copper 0.0175 mm 0 Dielectric 3 prepreg FR408HR 2113 0.2021 mm FR4 natural 3.6 0.01 Remy Nguyen B.Cu copper 0.0432 mm

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Date: 1/23/2024

Rev: B

ld: 1/1

Title: RF-DFS Gain Circuit

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Size: A4

B.Mask

B.Paste

Bottom Solder Mask Liquid Ink

Bottom Solder Paste

B.Silkscreen Bottom Silk Screen Liquid Photo

0.0254 mm

0 mm

0 mm

3.3

Purple

White

0

0

BOT-L4

2.50 mm 4 x Ø2.20 →·→ (M2)

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count: Board Thickness: 1.5670 mm

Board overall dimensions: 52.5000 mm x 40.5000 mm

Min track/spacing: 0.0000 mm / 0.0000 mm Min hole diameter: 0.3000 mm

Copper Finish: ENIG Impedance Control: Yes Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Notes: LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit				
Size: A4	Date: 1/23/2024	Rev: B		
KiCad E.D.A. kid	ad 7.0.5	ld: 1/1		